Material Composition Declaration

iS15M8R8S1C

Company Name:	**iDEAL Semiconductor Devices, Inc.**
Quality Contact:	**Deo Laranang**
Contact email:	**dlaranang@idealsemi.com**
Part Weight:	**67.2404 mg**

Material	Composition	CAS No.	% of weight	Weight (mg)
Wafer	Silicon	7440-21-3	100	3.303
Lead Frame	Cu	7440-50-8	96.24-97.335	52.5000
	Fe	7439-89-6	2.10 ~ 2.60	
	Pb	7439-92-1	0.01 Max.	
	P	7723-14-0	0.015 ~ 0.150	
	Zn	7440-66-6	0.050 ~ 0.200	
	Ag	7440-22-4	0.5-0.8	
Solder	Lead	7439-92-1	≥ 70 -< 90	2.6791
	Hydrogenated Rosin	65997-06-0	≥5-<10	
	Tin	7440-31-5	≥1-<5	
	Terpineol	8000-41-7	≥ 3 -< 5	
	silver	7440-22-4	≥1-<2.5	
	[(Butoxymethylethoxy)methylethoxy]propan-1-ol	55934-93-5	≥1-<5	
	Amines, N-coco alkyltrimethylenedi-	61791-63-7	≥ 0.25 -< 1	
	Reaction mass of :12-hydroxy-N-[2-[(1-oxodecyl)-,12-hydroxy-N-[2-[(1-oxooctyl)amino]alkyl]octadecanamide & Alkanebis-(12-Hydroxystearamide)	126098-16-6	≥0.25-<1	
Wire	Al	7429-90-5	>99.99	1.2591
	Ni	7440-02-0	<60ppm	
	Si	7440-21-3	<10ppm	

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	Fe	7439-89-6	<3ppm	
	Mg	7439-95-4	<3ppm	
	Cu	7440-50-8	<3ppm	
	B	7440-42-8	<1ppm	
	Ag	7440-22-4	<1ppm	
	Mn	7439-96-5	<1ppm	
	Ca	7440-70-2	<1ppm	
	Cr	7440-47-3	<1ppm	
	Au	7440-57-5	100.00%	0.0895
Mold Compound	Epoxy resin	Trade Secret	5~10	6.3400
	Phenol Resin	Trade Secret	1~5	
	Silica(Amorphous) A	60676-86-0	70~90	
	Silica(Amorphous) B	7631-86-9	5~10	
	Carbon black	1333-86-4	0.1~1	
Plating	Tin	7440-31-5	99.90	1.0697
	Other	.....	<0.1	
Total Weight				**67.2404**

Note: The substance content disclosed herewith is approximate and is based on engineering calculations. Statements are based on our present knowledge and may be subject to change at any time due to technical requirements and development. iDEAL Semiconductor may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.

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